



FEATURES:

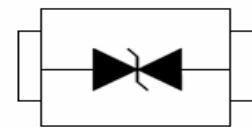
- 400 Watts peak pulse power per line ($t_P=8/20\mu s$)
- Protects one bi-directional I/O line
- Low clamping voltage
- Working voltage:15V
- Low leakage current
- RoHS compliant



SOD-323

MAIN APPLICATIONS

- Cell phone handsets and accessories
- Microprocessor based equipment
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- Portable instrumentation



Pin Configuration

PROTECTION SOLUTION TO MEET

- IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 10A (8/20 μs)

MECHANICAL CHARACTERISTICS

- SOD-323 package
- Molding compound flammability rating : UL 94V-0
- Weight 5 milligrams (approximate)
- Quantity per reel : 3,000pcs
- Lead finish : lead free
- Marking code Ö15B

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P _{PP}	400	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T _L	260 (10 sec.)	
Operating junction temperature range	T _J	-55 to +125	
Storage temperature range	T _{STG}	-55 to +150	

ELECTRICAL CHARACTERISTICS (V_{CC}=2.5V)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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FIG.3: Pulse derating curve

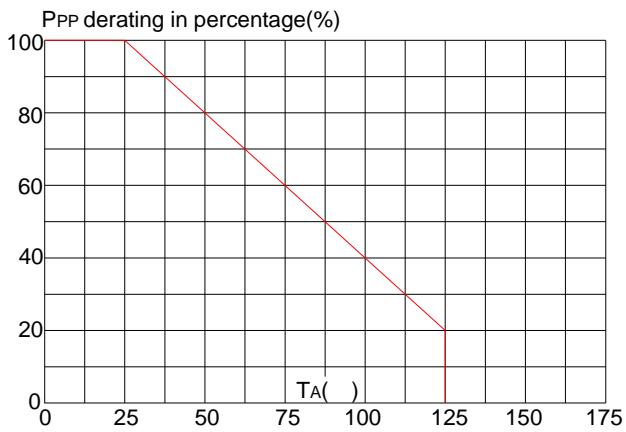
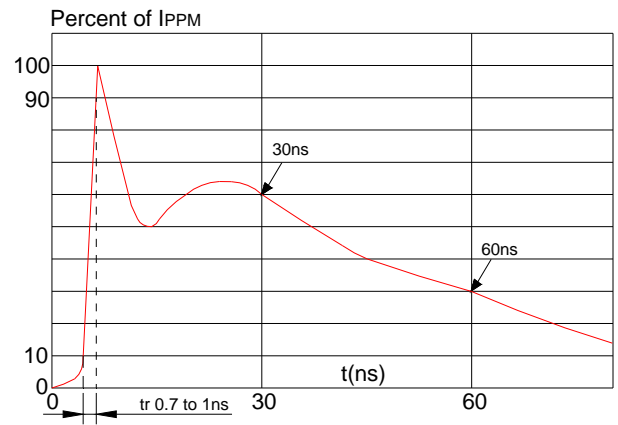
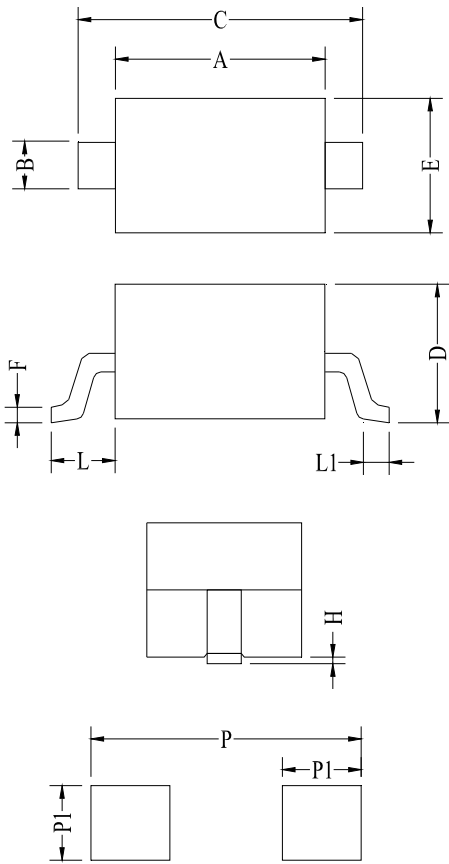


FIG.4: ESD clamping (30kV contact)



SOLDERING5D3

PACKAGE MECHANICAL DATA

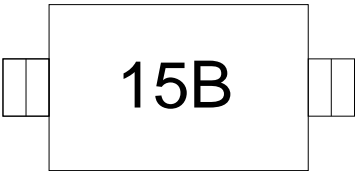


Land Pattern

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	1.60	1.70	1.80	0.063	0.067	0.071
B	0.25	0.32	0.40	0.010	0.013	0.016
C	2.30	2.60	2.80	0.091	0.102	0.110
D	0.80	0.95	1.10	0.031	0.037	0.043
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.08	0.13	0.18	0.003	0.005	0.007
L	0.475REF			0.019REF		
L1	0.25	0.33	0.40	0.010	0.013	0.016
H	0.00	0.06	0.14	0.000	0.002	0.006
P	3.00			0.118		
P1	0.80			0.031		

JEB15D3

MARKING CODE

Part Number	Marking Code
JEB15D3	

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